- Members of the Texas Instruments Widebus™ Family

- UBT™ Transceivers Combine D-Type Latches and D-Type Flip-Flops for Operation in Transparent, Latched, or Clocked Mode

- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})

- Support Unregulated Battery Operation Down to 2.7 V

- Typical V_{OLP} (Output Ground Bounce) <0.8 V at V_{CC} = 3.3 V, T_A = 25°C

- I_{off} and Power-Up 3-State Support Hot Insertion

- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors

- Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise

- Flow-Through Architecture Optimizes PCB Layout

- Latch-Up Performance Exceeds 500 mA Per JESD 17

- ESD Protection Exceeds JESD 22
  – 2000-V Human-Body Model (A114-A)
  – 200-V Machine Model (A115-A)
  – 1000-V Charged-Device Model (C101)

SN54LVTH16500 . . . WD PACKAGE
SN74LVTH16500 . . . DGG OR DL PACKAGE
(TOP VIEW)

OEAB	1	56	GND
LEAB	2	55	$\overline{CLKAB}$
A1	3	54	B1
GND	4	53	GND
A2	5	52	B2
A3	6	51	B3
V_{CC}	7	50	V_{CC}
A4	8	49	B4
A5	9	48	B5
A6	10	47	B6
GND	11	46	GND
A7	12	45	B7
A8	13	44	B8
A9	14	43	B9
A10	15	42	B10
A11	16	41	B11
A12	17	40	B12
GND	18	39	GND
A13	19	38	B13
A14	20	37	B14
A15	21	36	B15
V_{CC}	22	35	V_{CC}
A16	23	34	B16
A17	24	33	B17
GND	25	32	GND
A18	26	31	B18
$\overline{OEBA}$	27	30	$\overline{CLKBA}$
LEBA	28	29	GND

description/ordering information

The 'LVTH16500 devices are 18-bit universal bus transceivers designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 85°C	SSOP – DL	Tube	SN74LVTH16500DL	LVTH16500
		Tape and reel	SN74LVTH16500DLR	
	TSSOP – DGG	Tape and reel	SN74LVTH16500DGGR	LVTH16500
	VFBGA – GQL	Tape and reel	SN74LVTH16500GQLR	LL500
	VFBGA – ZQL (Pb-free)		SN74LVTH16500ZQLR	
−55°C to 125°C	CFP – WD	Tube	SNJ54LVTH16500WD	SNJ54LVTH16500WD

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

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description/ordering information (continued)

Data flow in each direction is controlled by output-enable (OEAB and $\overline{\text{OEBA}}$), latch-enable (LEAB and LEBA), and clock ($\overline{\text{CLKAB}}$ and $\overline{\text{CLKBA}}$) inputs. For A-to-B data flow, the devices operate in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if $\overline{\text{CLKAB}}$ is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the high-to-low transition of $\overline{\text{CLKAB}}$. OEAB is active high. When OEAB is high, the B-port outputs are active. When OEAB is low, the B-port outputs are in the high-impedance state.

Data flow for B to A is similar to that of A to B, but uses $\overline{\text{OEBA}}$, LEBA, and $\overline{\text{CLKBA}}$. The output enables are complementary (OEAB is active high and $\overline{\text{OEBA}}$ is active low).

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

When V_{CC} is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor and OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

GQL OR ZQL PACKAGE
(TOP VIEW)
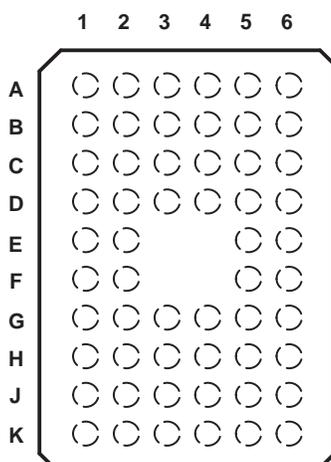
terminal assignments

	1	2	3	4	5	6
A	A1	LEAB	OEAB	GND	$\overline{\text{CLKAB}}$	B1
B	A3	A2	GND	GND	B2	B3
C	A5	A4	V_{CC}	V_{CC}	B4	B5
D	A7	A6	GND	GND	B6	B7
E	A9	A8			B8	B9
F	A10	A11			B11	B10
G	A12	A13	GND	GND	B13	B12
H	A14	A15	V_{CC}	V_{CC}	B15	B14
J	A16	A17	GND	GND	B17	B16
K	A18	$\overline{\text{OEBA}}$	LEBA	GND	$\overline{\text{CLKBA}}$	B18

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FUNCTION TABLE[†]

INPUTS				OUTPUT
OEAB	LEAB	$\overline{\text{CLKAB}}$	A	B
L	X	X	X	Z
H	H	X	L	L
H	H	X	H	H
H	L	↓	L	L
H	L	↓	H	H
H	L	H	X	B_0[‡]
H	L	L	X	B_0[§]

[†] A-to-B data flow is shown: B-to-A flow is similar, but uses $\overline{\text{OEBA}}$, LEBA, and $\overline{\text{CLKBA}}$.

[‡] Output level before the indicated steady-state input conditions were established

[§] Output level before the indicated steady-state input conditions were established, provided that $\overline{\text{CLKAB}}$ was low before LEAB went low

logic diagram (positive logic)

To 17 Other Channels
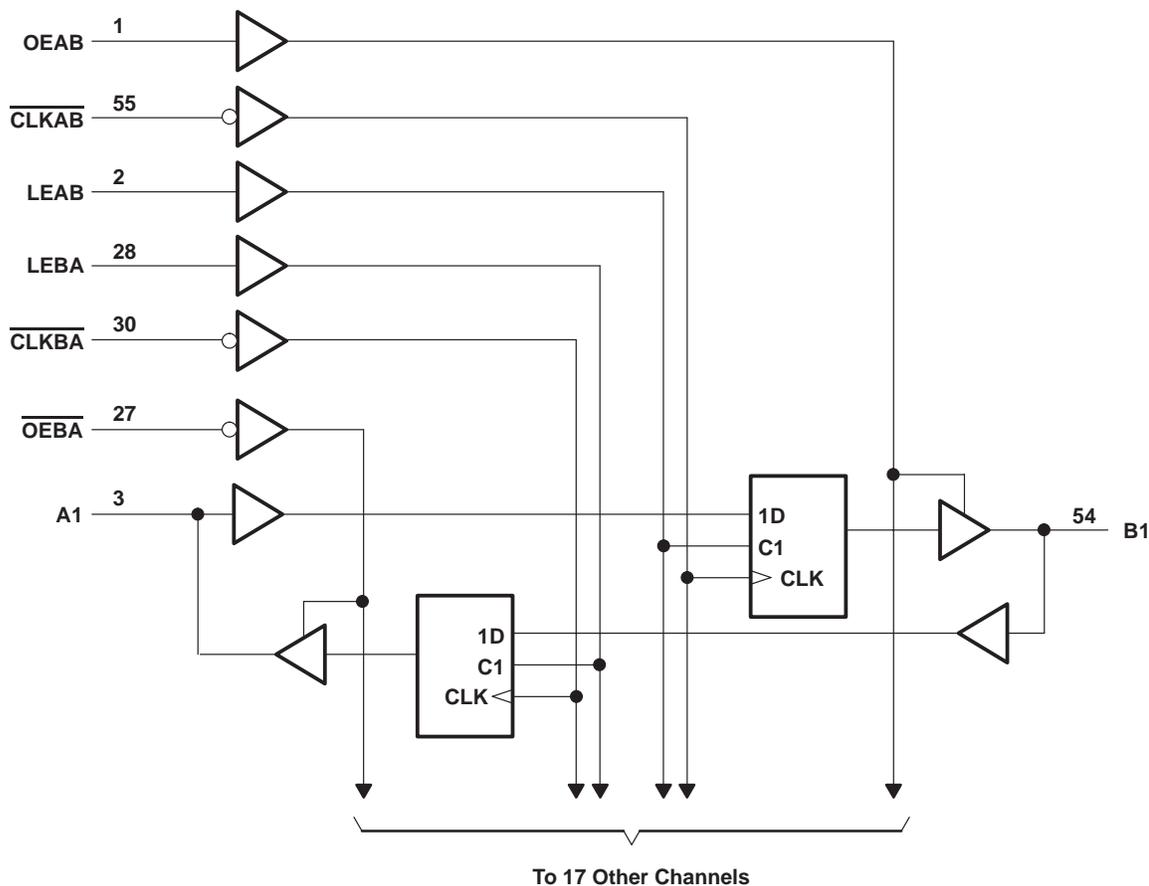
Pin numbers shown are for the DGG, DL, and WD packages.

3

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . –0.5 V to 4.6 V

Input voltage range, V_I (see Note 1) . . . . –0.5 V to 7 V

Voltage range applied to any output in the high-impedance
   or power-off state, V_O (see Note 1) . . . . –0.5 V to 7 V

Voltage range applied to any output in the high state, V_O (see Note 1) . . . . –0.5 V to V_{CC} + 0.5 V

Current into any output in the low state, I_O: SN54LVTH16500 . . . . 96 mA
                                        SN74LVTH16500 . . . . 128 mA

Current into any output in the high state, I_O (see Note 2):   SN54LVTH16500 . . . . 48 mA
                                                         SN74LVTH16500 . . . . 64 mA

Input clamp current, I_{IK} (V_I < 0) . . . . –50 mA

Output clamp current, I_{OK} (V_O < 0) . . . . –50 mA

Package thermal impedance, θ_{JA} (see Note 3):   DGG package . . . . 64°C/W
                                             DL package . . . . 56°C/W
                                             GQL/ZQL package . . . . 42°C/W

Storage temperature range, T_{stg} . . . . –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and
  functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not
  implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
          2. This current flows only when the output is in the high state and V_O > V_{CC}.
          3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

			SN54LVTH16500		SN74LVTH16500		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2.7	3.6	2.7	3.6	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage			5.5		5.5	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report,
         Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54LVTH16500 MIN	TYP†	MAX	SN74LVTH16500 MIN	TYP†	MAX	UNIT
V_{IK}		V_{CC} = 2.7 V,	I_I = −18 mA			−1.2			−1.2	V
V_{OH}		V_{CC} = 2.7 V to 3.6 V,	I_{OH} = −100 µA	V_{CC}−0.2			V_{CC}−0.2			V
		V_{CC} = 2.7 V,	I_{OH} = −8 mA	2.4			2.4			
		V_{CC} = 3 V	I_{OH} = −24 mA	2						
			I_{OH} = −32 mA				2			
V_{OL}		V_{CC} = 2.7 V	I_{OL} = 100 µA			0.2			0.2	V
			I_{OL} = 24 mA			0.5			0.5	
		V_{CC} = 3 V	I_{OL} = 16 mA			0.4			0.4	
			I_{OL} = 32 mA			0.5			0.5	
			I_{OL} = 48 mA			0.55				
			I_{OL} = 64 mA						0.55	
I_I	Control inputs	V_{CC} = 3.6 V,	V_I = V_{CC} or GND			±1			±1	µA
		V_{CC} = 0 or 3.6 V,	V_I = 5.5 V			10			10	
	A or B ports‡	V_{CC} = 3.6 V	V_I = 5.5 V			20			20	
			V_I = V_{CC}			1			1	
			V_I = 0			−5			−5	
I_{off}		V_{CC} = 0,	V_I or V_O = 0 to 4.5 V						±100	µA
$I_{I(hold)}$	A or B ports	V_{CC} = 3 V	V_I = 0.8 V	75			75			µA
			V_I = 2 V	−75			−75			
		V_{CC} = 3.6 V§,	V_I = 0 to 3.6 V						±500	
I_{OZPU}		V_{CC} = 0 to 1.5 V, V_O = 0.5 V to 3 V, $\overline{OE}$/OE = don't care				±100*			±100	µA
I_{OZPD}		V_{CC} = 1.5 V to 0, V_O = 0.5 V to 3 V, $\overline{OE}$/OE = don't care				±100*			±100	µA
I_{CC}		V_{CC} = 3.6 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			0.19			0.19	mA
			Outputs low			5			5	
			Outputs disabled			0.19			0.19	
ΔI_{CC}¶		V_{CC} = 3 V to 3.6 V, One input at V_{CC} − 0.6 V, Other inputs at V_{CC} or GND				0.2			0.2	mA
C_i		V_I = 3 V or 0			4			4		pF
C_{io}		V_O = 3 V or 0			10			10		pF

* On products compliant to MIL-PRF-38535, this parameter is not production tested.
† All typical values are at V_{CC} = 3.3 V, T_A = 25°C.
‡ Unused pins at V_{CC} or GND
§ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			SN54LVTH16500				SN74LVTH16500				UNIT
			V_{CC} = 3.3 V ± 0.3 V		V_{CC} = 2.7 V		V_{CC} = 3.3 V ± 0.3 V		V_{CC} = 2.7 V		
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency			150		150		150		150	MHz
t_w	Pulse duration	LE high	3.3		3.3		3.3		3.3		ns
		$\overline{CLK}$ high or low	3.3		3.3		3.3		3.3		
t_{su}	Setup time	A before $\overline{CLKAB}$↓	3.1		3.1		2.9		2.9		ns
		B before $\overline{CLKBA}$↓	3.1		3.1		2.9		2.9		
		A or B before LE↓ — $\overline{CLK}$ high	1.5		0.6		1.4		0.5		
		A or B before LE↓ — $\overline{CLK}$ low	3.1		2.5		2.9		2.3		
t_h	Hold time	A or B after $\overline{CLK}$↓	0.4		0.4		0.4		0.4		ns
		A or B after LE↓	1.7		1.7		1.6		1.6		

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54LVTH16500				SN74LVTH16500					UNIT
			V_{CC} = 3.3 V ± 0.3 V		V_{CC} = 2.7 V		V_{CC} = 3.3 V ± 0.3 V			V_{CC} = 2.7 V		UNIT
			MIN	MAX	MIN	MAX	MIN	TYP[†]	MAX	MIN	MAX	
f_{max}			150		150		150			150		MHz
t_{PLH}	B or A	A or B	1.2	3.9		4.1	1.3	2.8	3.7		4	ns
t_{PHL}			1.2	3.9		4.1	1.3	2.6	3.7		4	
t_{PLH}	LEBA or LEAB	A or B	1.4	5.5		5.9	1.5	3.8	5.1		5.7	ns
t_{PHL}			1.4	5.5		5.9	1.5	3.8	5.1		5.7	
t_{PLH}	$\overline{CLKBA}$ or $\overline{CLKAB}$	A or B	1.2	5.3		6.1	1.3	3.6	5		5.9	ns
t_{PHL}			1.2	5.3		6.1	1.3	3.5	5		5.9	
t_{PZH}	$\overline{OEBA}$ or OEAB	A or B	1.2	5.1		5.8	1.3	3.6	4.8		5.5	ns
t_{PZL}			1.2	5.1		5.8	1.3	3.6	4.8		5.5	
t_{PHZ}	$\overline{OEBA}$ or OEAB	A or B	1.6	6.1		6.6	1.7	4.5	5.8		6.3	ns
t_{PLZ}			1.6	6.1		6.6	1.7	4.1	5.8		6.3	

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

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PARAMETER MEASUREMENT INFORMATION

TEST	S1
t_{PHL}/t_{PLH}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND
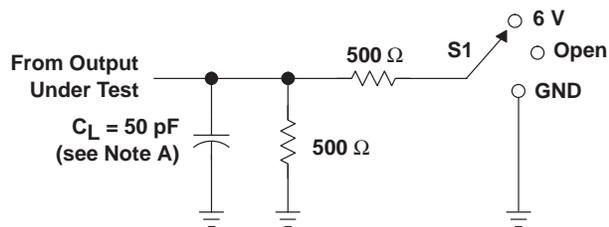
LOAD CIRCUIT
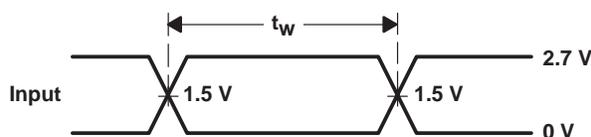
VOLTAGE WAVEFORMS
PULSE DURATION
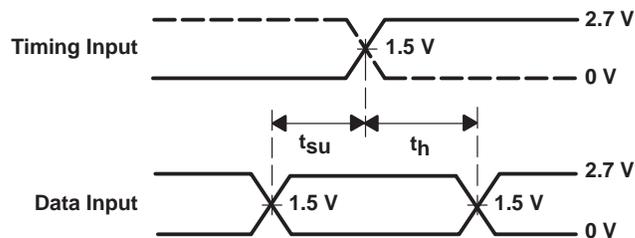
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES

VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS
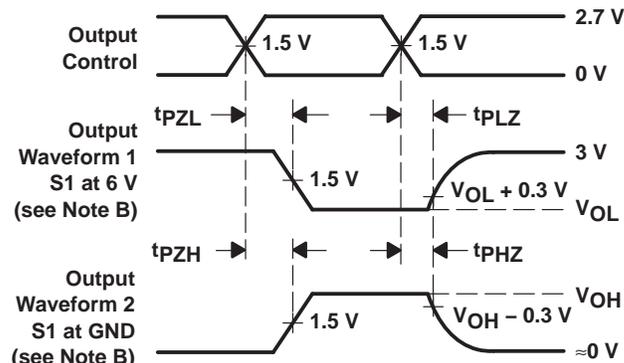
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
74LVTH16500DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16500	Samples
74LVTH16500DGGRG4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16500	Samples
SN74LVTH16500DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16500	Samples
SN74LVTH16500DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16500	Samples
SN74LVTH16500DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16500	Samples
SN74LVTH16500GQLR	OBSOLETE	BGA MICROSTAR JUNIOR	GQL	56		TBD	Call TI	Call TI	-40 to 85	LL500	

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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OTHER QUALIFIED VERSIONS OF SN74LVTH16500 :

● Enhanced Product: SN74LVTH16500-EP

NOTE: Qualified Version Definitions:

● Enhanced Product - Supports Defense, Aerospace and Medical Applications

![Texas Instruments logo] **PACKAGE MATERIALS INFORMATION**

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers
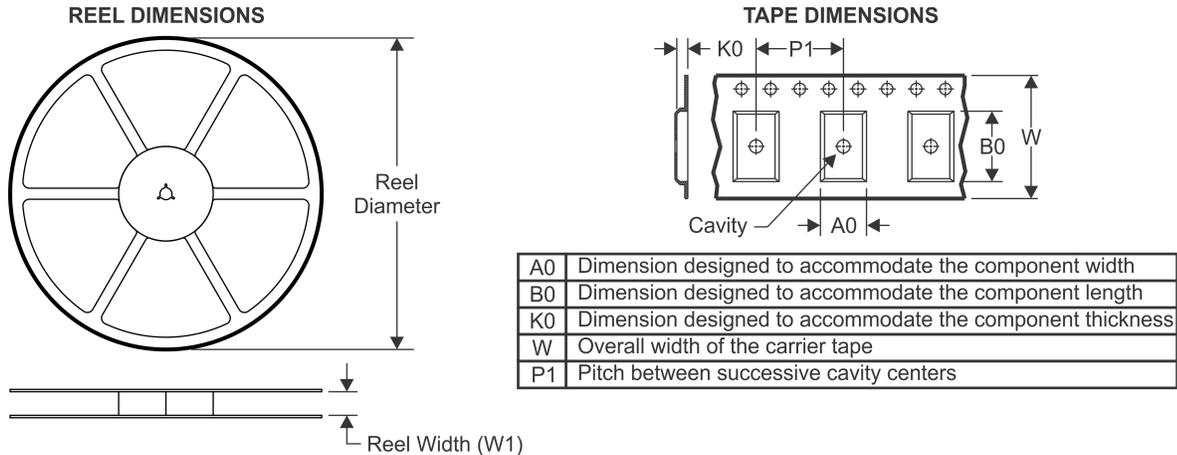
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVTH16500DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVTH16500DGGR	TSSOP	DGG	56	2000	367.0	367.0	45.0

DL (R−PDSO−G56) PLASTIC SMALL−OUTLINE PACKAGE

0.025 (0,635)

0.0135 (0,343)
0.008 (0,203)

⊕ 0.005 (0,13) Ⓜ

56

29

0.420 (10,67)
0.395 (10,03)

0.010 (0,25)
0.005 (0,13)

0.299 (7,59)
0.291 (7,39)

Gage Plane

0.010 (0,25)

1

28

0°−8°

0.040 (1,02)
0.020 (0,51)

0.730 (18,54)
0.720 (18,29)

0.110 (2,79) MAX

0.008 (0,20) MIN

Seating Plane

◁ 0.004 (0,10)

4040048−4/F 05/13
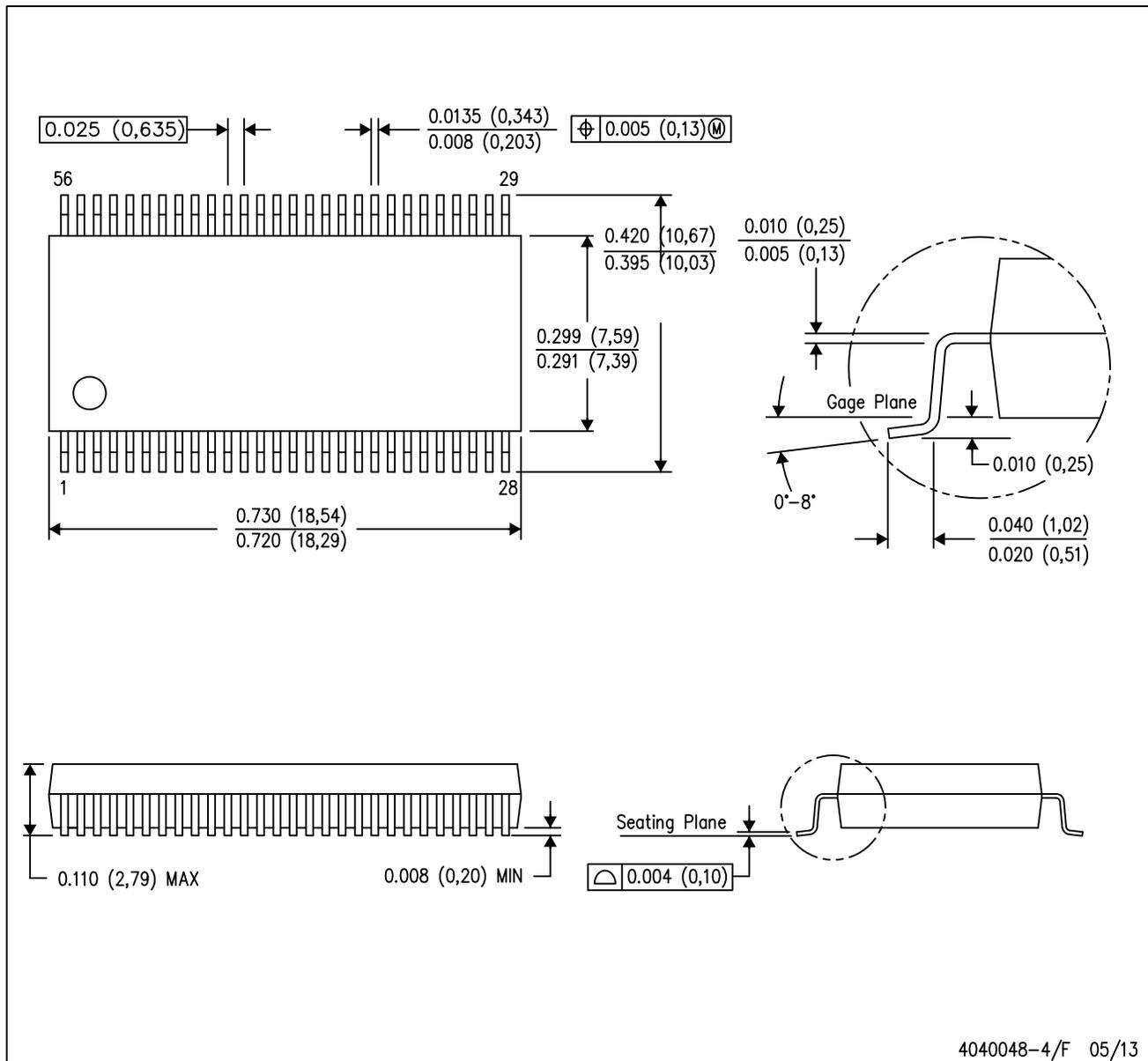
NOTES: A. All linear dimensions are in inches (millimeters).
        B. This drawing is subject to change without notice.
        C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
        D. Falls within JEDEC MO−118

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GQL (R−PBGA−N56)   PLASTIC BALL GRID ARRAY

4,60 / 4,40   B

A

7,10 / 6,90

A1 Corner

1,00 Max

0,10 C

Seating Plane

0,35 / 0,15   C

3,25

0,65

0,325

K
J
H
G
F
E
D
C
B
A

1 2 3 4 5 6

Bottom View

3X Via Hole
Without Ball

Missing Via Hole
Indicates Pin A1
Quadrant

0,65

5,85

0,325

56X Ø 0,45 / 0,35

⊕ Ø 0,15 Ⓜ C A B
   Ø 0,08 Ⓜ C

4200583−3/K 06/2007
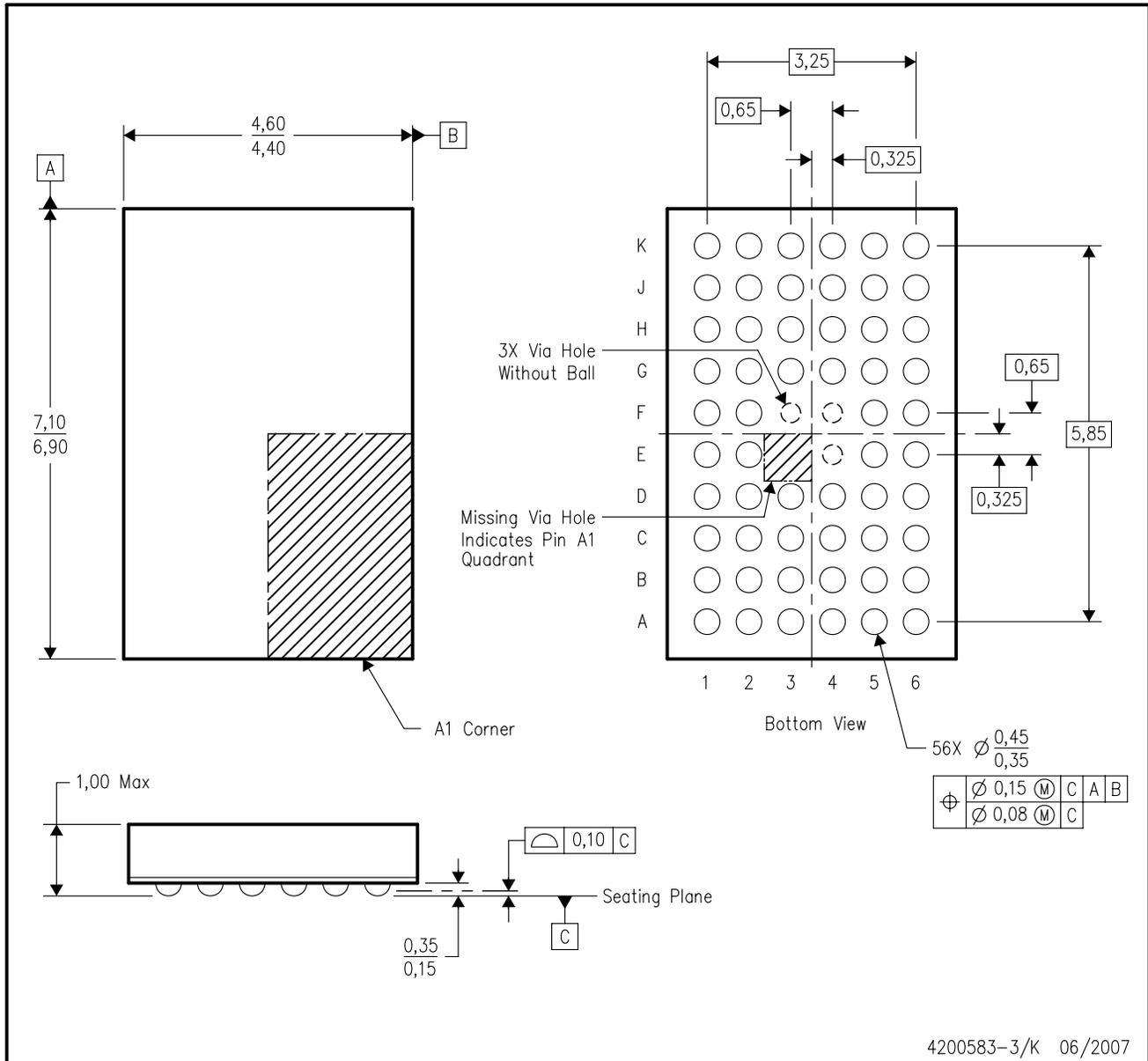
NOTES: A.   All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M−1994.
         B.   This drawing is subject to change without notice.
         C.   Falls within JEDEC MO−285 variation BA−2.
         D.   This package is tin−lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead−free.

TEXAS
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DGG (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE PACKAGE**

48 PINS SHOWN

	PINS **	48	56	64
DIM				
A MAX		12,60	14,10	17,10
A MIN		12,40	13,90	16,90

4040078 / F 12/97
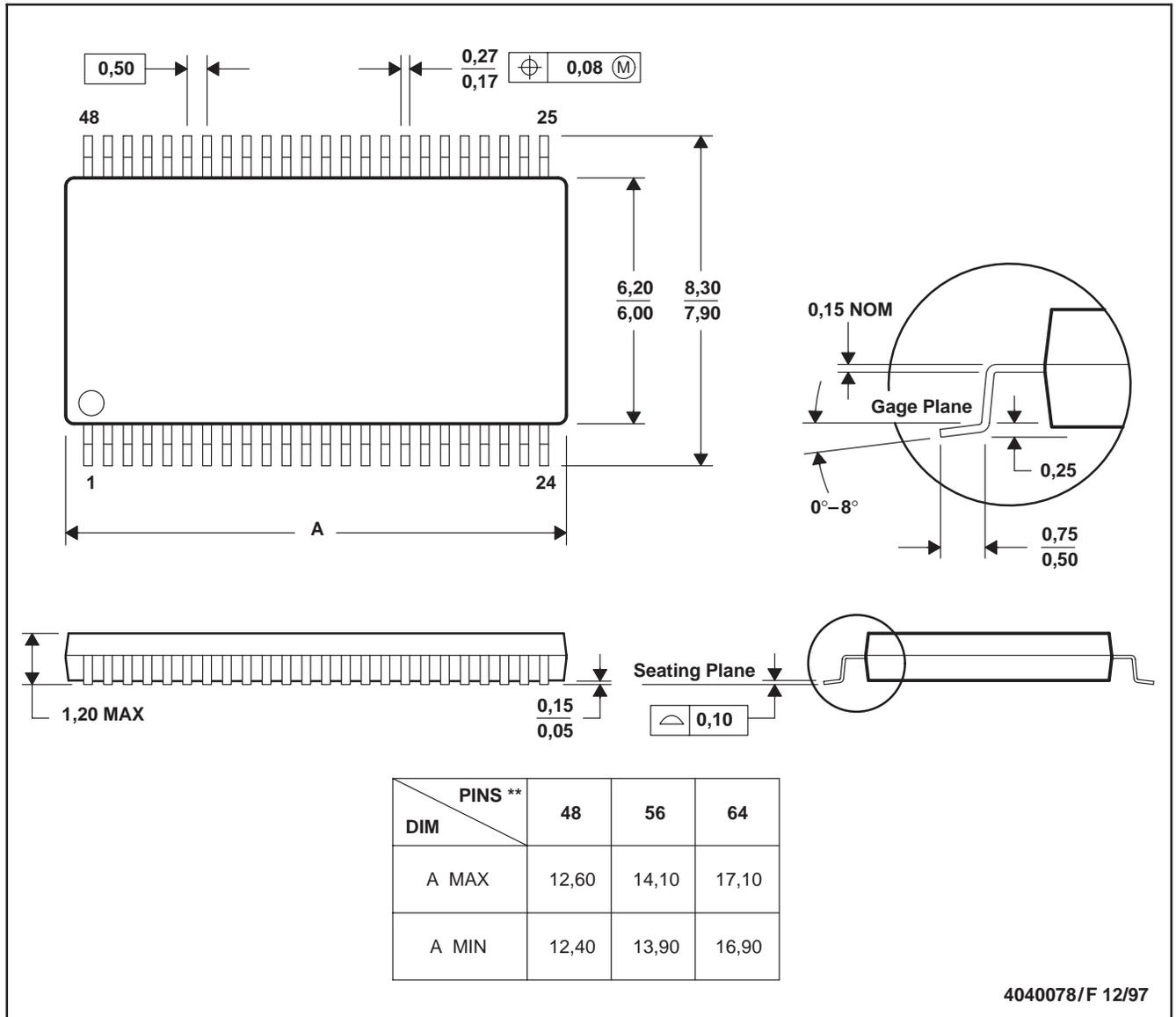
NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

TEXAS INSTRUMENTS

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